## 2SD2413

## Silicon NPN triple diffusion planar type

## For low-frequency output amplification

## Features

- High collector-base voltage (Emitter open) $\mathrm{V}_{\mathrm{CBO}}$
- High collector-emitter voltage (Base open) $\mathrm{V}_{\mathrm{CEO}}$
- Large collector power dissipation $\mathrm{P}_{\mathrm{C}}$
- Low collector-emitter saturation voltage $\mathrm{V}_{\mathrm{CE}(\text { sat })}$
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

Absolute Maximum Ratings $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$

| Parameter | Symbol | Rating | Unit |
| :--- | :---: | :---: | :---: |
| Collector-base voltage (Emitter open) | $\mathrm{V}_{\mathrm{CBO}}$ | 400 | V |
| Collector-emitter voltage (Base open) | $\mathrm{V}_{\text {CEO }}$ | 400 | V |
| Emitter-base voltage (Collector open) | $\mathrm{V}_{\mathrm{EBO}}$ | 5 | V |
| Collector current | $\mathrm{I}_{\mathrm{C}}$ | 100 | mA |
| Peak collector current | $\mathrm{I}_{\mathrm{CP}}$ | 200 | mA |
| Collector power dissipation ${ }^{*}$ | $\mathrm{P}_{\mathrm{C}}$ | 1 | W |
| Junction temperature | $\mathrm{T}_{\mathrm{j}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

Note) *: Printed circuit board: Copper foil area of $1 \mathrm{~cm}^{2}$ or more, and the board thickness of 1.7 mm for the collector portion

Electrical Characteristics $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max |
| :--- | :---: | :--- | :---: | :---: | :---: |
| Collector-base voltage (Emitter open) | $\mathrm{V}_{\mathrm{CBO}}$ | $\mathrm{I}_{\mathrm{C}}=100 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{E}}=0$ | 400 |  |  |
| Collector-emitter voltage (Base open) | $\mathrm{V}_{\mathrm{CEO}}$ | $\mathrm{I}_{\mathrm{C}}=500 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=0$ | 400 |  |  |
| Emitter-base voltage (Collector open) | $\mathrm{V}_{\mathrm{EBO}}$ | $\mathrm{I}_{\mathrm{E}}=100 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{C}}=0$ | 5 |  |  |
| Forward current transfer ratio | $\mathrm{h}_{\mathrm{FE}}$ | $\mathrm{V}_{\mathrm{CE}}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=30 \mathrm{~mA}$ | 30 |  |  |
| Collector-emitter saturation voltage | $\mathrm{V}_{\mathrm{CE}(\text { sat })}$ | $\mathrm{I}_{\mathrm{C}}=50 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=5 \mathrm{~mA}$ |  |  | 1.5 |
| Base-emitter saturation voltage | $\mathrm{V}_{\mathrm{BE}(\text { sat })}$ | $\mathrm{I}_{\mathrm{C}}=50 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=5 \mathrm{~mA}$ | V |  |  |
| Transition frequency * | $\mathrm{f}_{\mathrm{T}}$ | $\mathrm{V}_{\mathrm{CB}}=30 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=-20 \mathrm{~mA}, \mathrm{f}=200 \mathrm{MHz}$ |  | 40 |  |
| Collector output capacitance <br> (Common base, input open circuited) | $\mathrm{C}_{\mathrm{ob}}$ | $\mathrm{V}_{\mathrm{CB}}=30 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=0, \mathrm{f}=1 \mathrm{MHz}$ |  |  | 7 |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *: Pulse measurement







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